

100V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

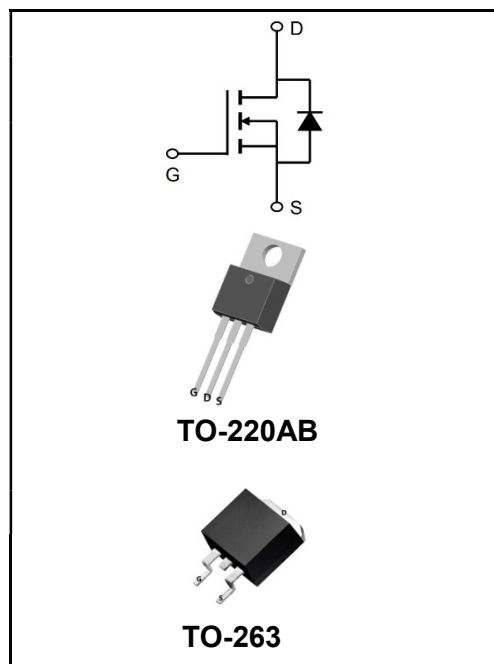
I_D	140A
V_{DSS}	100V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 4.2m Ω (Type: 3.5m Ω)

Features

- ♦ Ultra-low RDS(ON)
- ♦ Low Gate Charge
- ♦ High Current Capability
- ♦ 100% UIS Tested, 100% Rg Tested


Application

- ♦ Power Management in Telecom., Industrial Automation, CE
- ♦ Motor Driving in Power Tool, E-vehicle, Robotics
- ♦ Current Switching in DC/DC & AC/DC (SR) Sub-systems


Product Specification Classification

Part Number	Package	Marking	Pack
YFW100N035AT	TO-220AB	YFW 100N035AT XXXXX	1000PCS/Tape
YFW100N035AS-R	TO-263	YFW 100N035AS XXXXX	800PCS/Tube

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, (@Note1)	I_D	140	A
Continuous Drain Current, @Tc=100°C (@Note1)	I_D	88	A
Pulsed Drain Current (@Note2)	I_{DM}	426	A
Single Pulse Avalanche Energy (@Note3)	E_{AS}	151	mJ
Avalanche Current (@Note2)	I_{AS}	55	A
Total Power Dissipation ⁴ @Tc=25°C (@Note4)	P_D	156	W
Total Power Dissipation ⁴ @Tc=100°C (@Note4)		63	
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance, Junction-ambient	$R_{\theta JA}$	45	°C/W
Thermal Resistance, Junction-case	$R_{\theta JC}$	0.65	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition		Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$		BV_{DSS}	100	110	-	V
Gate -Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$		I_{GSS}	-	-	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$		I_{DSS}	-	-	1	μA
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$		$V_{GS(th)}$	2.0	2.7	4.0	V
Drain-Source on-Resistance	$V_{GS}=10V, I_D=20A$	TO-220	$R_{DS(on)}$	-	3.5	4.2	m Ω
		TO-263		-	3.5	4.2	
Forward Transconductance	$V_{DS}=5V, I_D=20A$		G_{FS}	-	106	-	S
Input Capacitance	$V_{DS}=50V$ $V_{GS}=0V$ $f=1MHz$		C_{iss}	-	3433	-	pF
Output Capacitance			C_{oss}	-	905	-	
Reverse Transfer Capacitance			C_{rss}	-	13	-	
Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		R_g	-	2.1	-	Ω
Turn-on delay time	$V_{GS}=10V$ $V_{DS}=50V$ $R_G=6\Omega$ $R_L=2.5\Omega$		$t_{d(on)}$	-	14.1	-	nS
Rise Time			T_r	-	34	-	
Turn-Off Delay Time			$t_{d(OFF)}$	-	60	-	
Fall Time			t_f	-	50	-	
Total Gate Charge	$V_{DS}=50V$ $V_{GS}=10V$ $I_D=20A$		Q_g	-	57	-	nC
Gate-Source Charge			Q_{gs}	-	11	-	
Gate-Drain Charge			Q_{gd}	-	16.1	-	
Diode Forward Voltage ²	$V_{GS}=0V, I_F=1A$		V_{SD}	-	0.7	1.0	V
Continuous Source Current ^{1,5}	TC = 25°C		I_S	-	-	156	A
Body Diode Reverse Recovery Time	$I_F=20A, di_{SD}/dt=100A/\mu s$ TJ = 25°C,		t_{rr}	-	78	-	nS
Body Diode Reverse Recovery Charge			Q_{rr}	-	180	-	nC

Notes:

1. Computed continuous current assumes the condition of TJ_Max while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under TJ_Max = 150°C.
3. This single-pulse measurement was taken under the following condition [L = 100 μ H, VGS = 10V, VDS = 50V] while its value is limited by TJ_Max = 150°C.
4. The power dissipation PD is based on TJ_Max = 150°C.
5. This value is guaranteed by design hence it is not included in the production tes

Ratings and Characteristic Curves

Typical Electrical & Thermal Characteristics

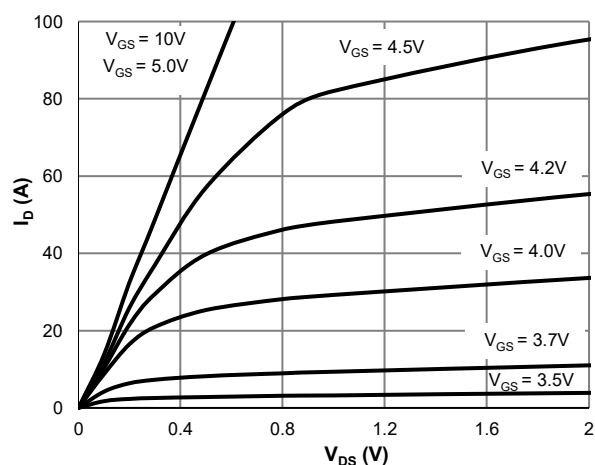


Figure 1: Saturation Characteristics

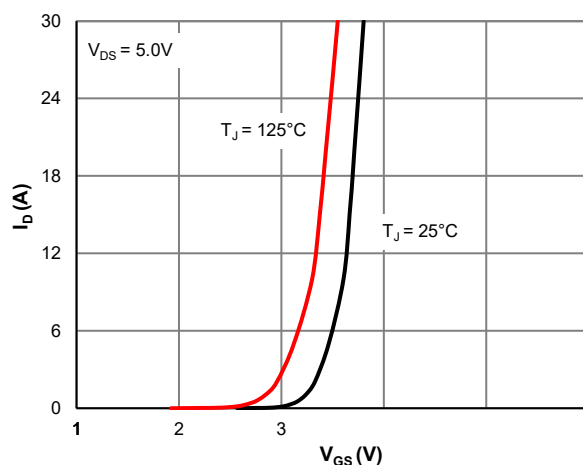


Figure 2: Transfer Characteristics

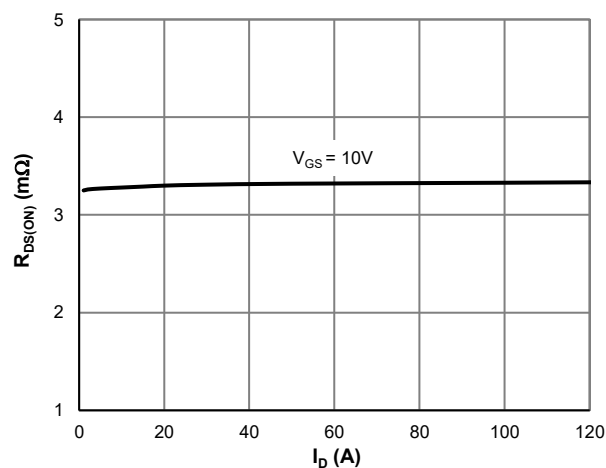


Figure 3: $R_{DS(ON)}$ vs. Drain Current

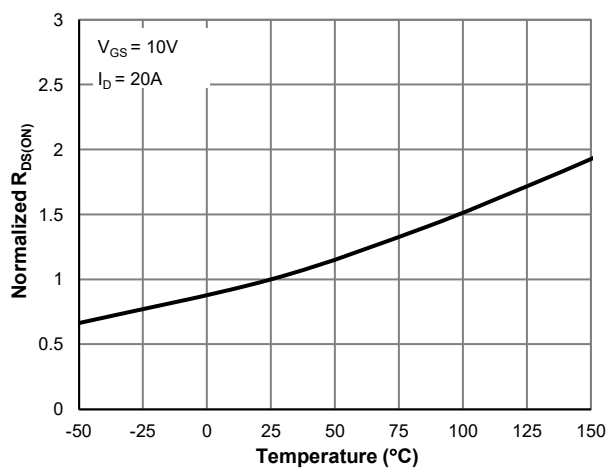


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

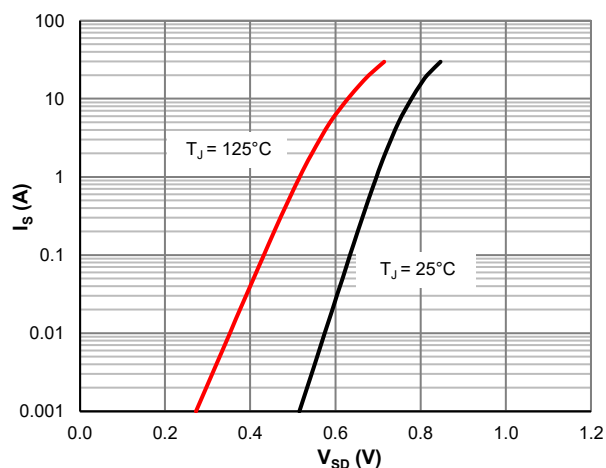


Figure 5: Body-Diode Characteristics

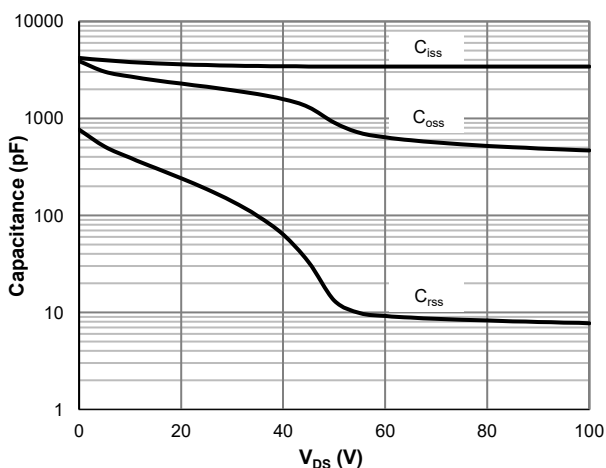


Figure 6: Capacitance Characteristics

Ratings and Characteristic Curves

Typical Electrical & Thermal Characteristics

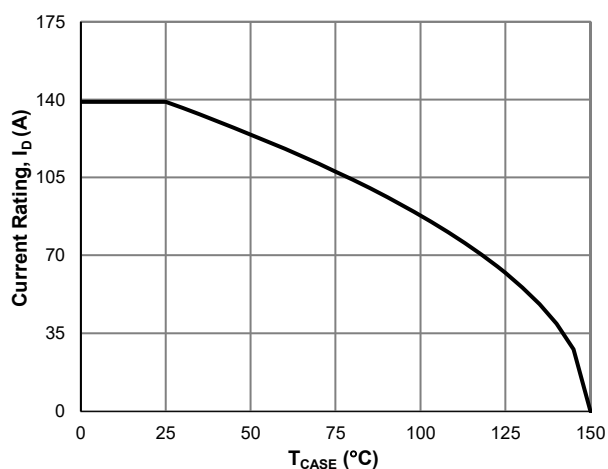


Figure 7: Current De-rating

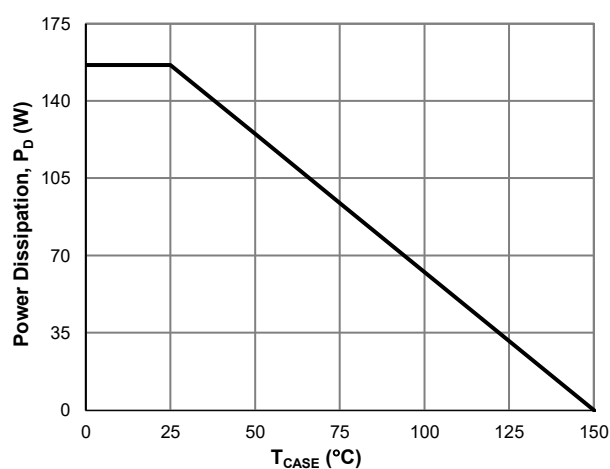


Figure 8: Power De-rating

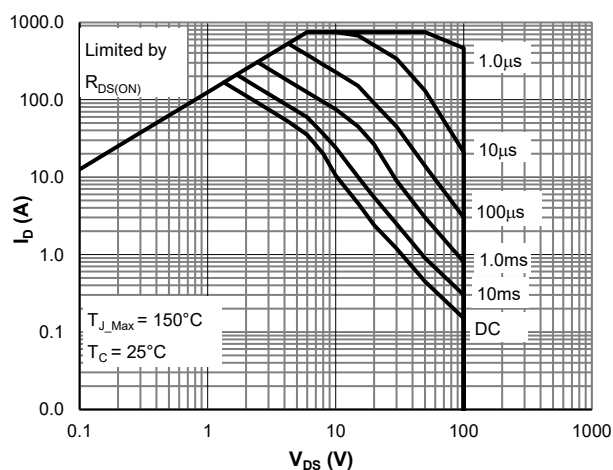


Figure 9: Maximum Safe Operating Area

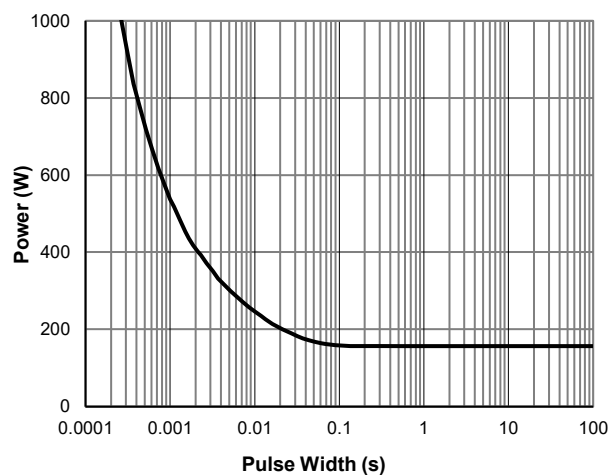


Figure 10: Single Pulse Power Rating, Junction-to-Case

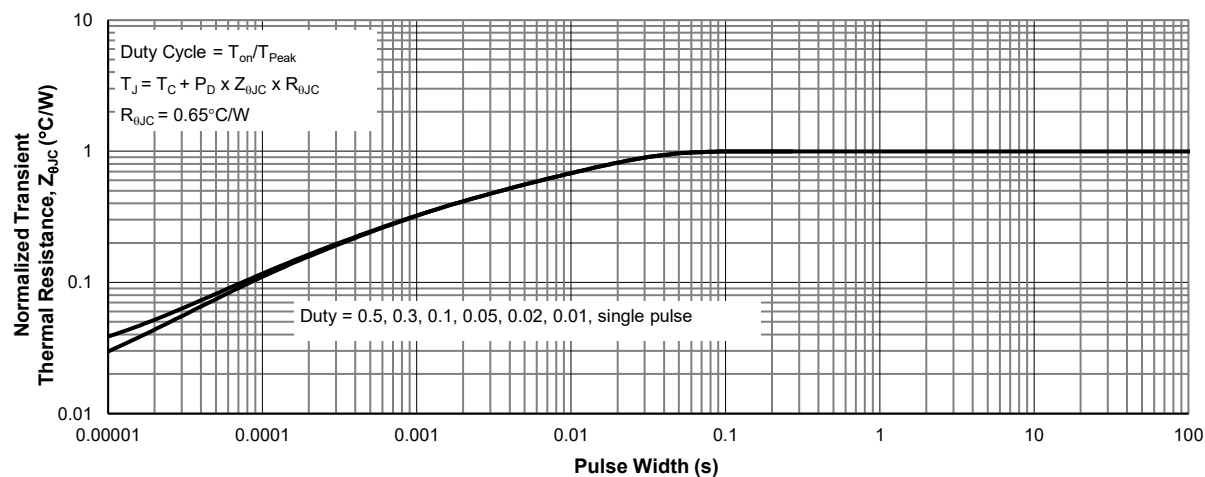
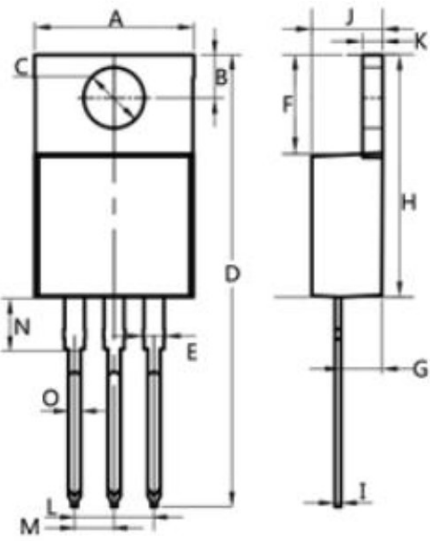


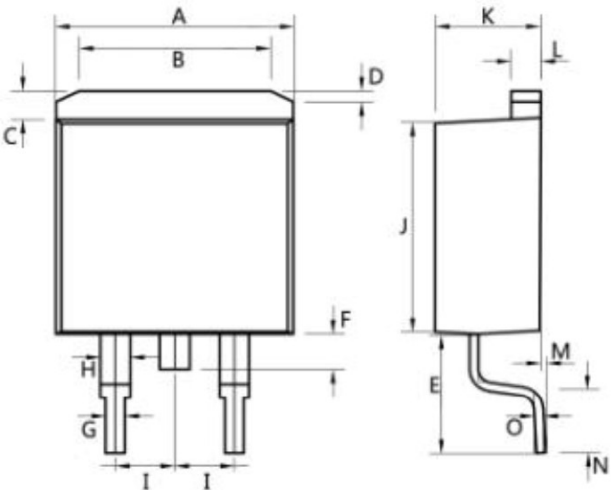
Figure 11: Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions Millimeters

TO-220AB

	Dim.	Min.	Max.
	A	10.15	10.35
	B	2.65	2.95
	C	3.70	3.90
	D	28.5	29.5
	E	1.30	1.45
	F	6.35	6.55
	G	2.9	3.3
	H	15.0	16.0
	I	0.38	0.42
	J	4.45	4.55
	K	1.25	1.35
	L	Typ 5.08	
	M	Typ 2.54	
	N	3.1	3.3
	O	0.76	0.84
All Dimensions in millimeter			

TO-263

	Dim.	Min.	Max.
	A	10.1	10.2
	B	7.4	7.6
	C	1.3	1.5
	D	0.55	0.75
	E	5.0	6.0
	F	1.4	1.6
	G	0.78	0.86
	H	1.2	1.3
	I	Typ2.54	
	J	8.4	8.6
	K	4.45	4.55
	L	1.25	1.35
	M	0.02	0.1
	N	2.4	2.8
	O	0.36	0.40
All Dimensions in millimeter			